

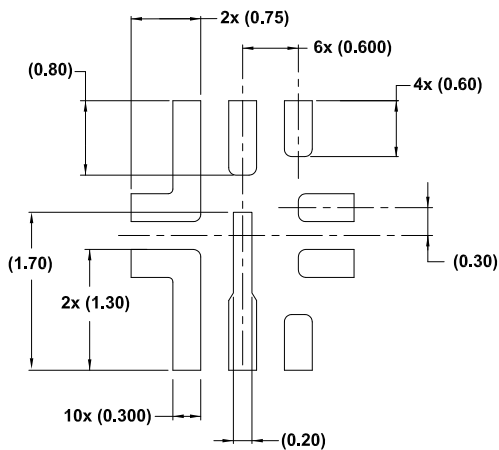
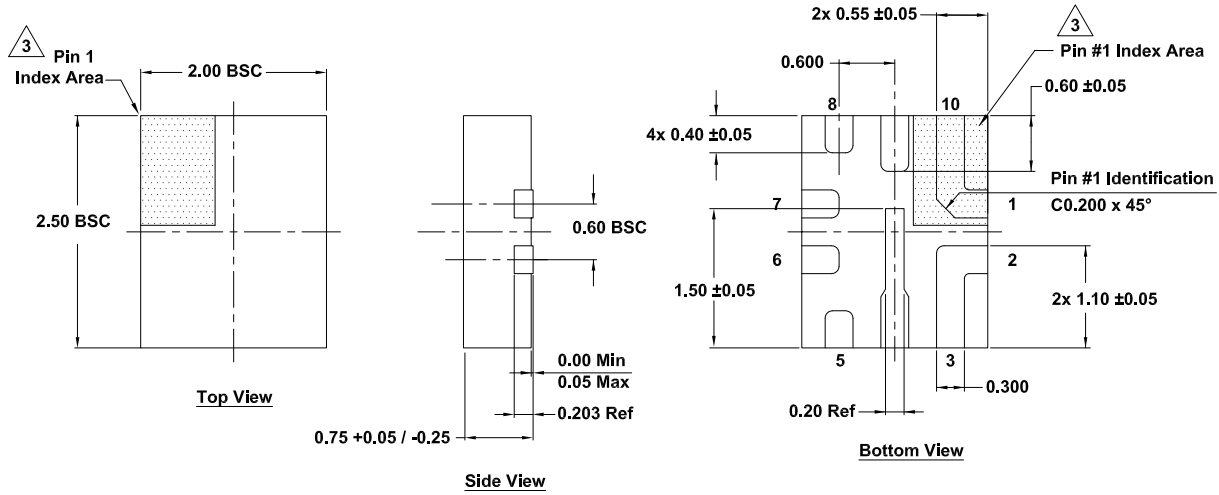
# Plastic Packages for Integrated Circuits

## Package Outline Drawing

L10.2x2.5

10 Lead 2x2.5 Flip Chip Quad Flat No-Lead Package (FCQFN)

Rev 0, 7/20



Typical Recommended Land Pattern

### Notes:

1. Dimensions are in millimeters. Dimensions in ( ) for reference only.
2. Dimensioning and tolerancing conform to ASME Y14.5m-1994.
3. The configuration of the pin #1 identifier is optional, but must be located within the zone indicated. The pin #1 identifier can be either a mold or mark feature.
4. Unless otherwise specified, tolerance: Decimal ±0.05